

VHF chokes

 Series/Type:
 B82111E

 Date:
 May 2022

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B82111E

Inductors

VHF chokes

Rated voltage 500 V AC/DC Rated current 0.2 ... 5 A Rated inductance 7 ... 680 µH

Construction

- Ferrite cylinder core
- Winding: single-layer, enamel copper wire
- Polyester insulating sleeve

Features

- High resonant frequency
- Wide inductance range
- Design complies with EN 60938
- Suitable for wave soldering
- RoHS-compatible

Applications

- RF blocking and filtering
- Interference suppression in small appliances
- Decoupling in telecommunications and entertainment electronics

Terminals

- Central axial leads
- Base material Cu
- Hot-dip tinned with pure tin

Marking

L_R and I_R in clear text

Delivery mode and packing unit

- Taped and reeled
- Packing unit: 1000 pcs./reel



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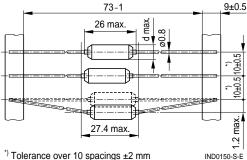


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Dimensional drawing



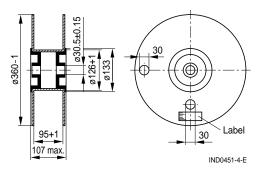
*) Tolerance over 10 spacings ±2 mm



Dimensions in mm

Reel packing

B82111E*C020 ... C028



Dimensions in mm



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Technical data and measuring conditions

Test voltage V _{test}	2500 V AC, 1 min				
Rated inductance L _R	$\begin{array}{llllllllllllllllllllllllllllllllllll$				
Inductance tolerance	±20%				
Rated temperature T _R	+60 °C				
Rated current I _R	Maximum permissible DC current at rated temperature				
DC resistance R _{typ}	Measured at +20 °C, tolerance ±20%, typical values				
Resonance frequency f _{res}	Measured with Agilent 4294A or 8753ES, or Keysight E990A or equivalent, +20 °C, tolerance ±30%				
Solderability (lead-free)	Sn95.5Ag3.8Cu0.7 or Sn96.5Ag3.0Cu0.5: +(245 ±5) °C, (3 ±0.3) s Wetting of soldering area ≥ 90% (to IEC 60068-2-20, test Ta)				
Resistance to soldering heat (wave soldering)	+(260 ±5) °C, 10 s (to IEC 60068-2-20, test Tb)				
Tensile strength of leads	acc. to IEC 60068-2-21, test Ua				
Climatic category	55/125/56 (to IEC 60068-1)				
Storage conditions Mounted: -55 °C +125 °C Packaged: -25 °C +40 °C, ≤ 75% RH					

Mounting information

When bending the leads, take care that the bending point is **at least 3 mm** apart from the face ends of the core and that the start-of-winding areas are not subjected to any mechanical stress.



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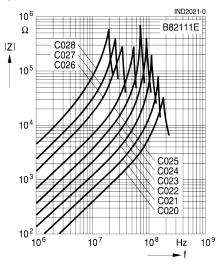
I _R	L _R	R _{typ}	f _{res}	Approx. weight	Dimensions d _{max}	Ordering code
А	μН	Ω	MHz	g	mm	
0.2	680	14	19	2.2	6.0	B82111E0000C028
0.3	470	6.5	25	2.3	6.0	B82111E0000C027
0.5	220	2.6	32	2.3	6.5	B82111E0000C026
1	100	0.65	55	2.5	6.5	B82111E0000C025
1.5	56	0.30	70	2.7	6.5	B82111E0000C024
2	40	0.18	90	3.0	7.0	B82111E0000C023
3	22	0.07	110	3.3	7.0	B82111E0000C022
4	12	0.04	140	3.5	7.5	B82111E0000C021
5	7	0.02	180	3.6	7.5	B82111E0001C020

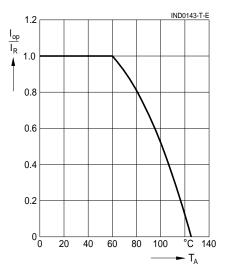
Characteristics and ordering codes

Impedance |Z| versus frequency f

measured with impedance analyzer Agilent 4294A or S-parameter network analyzer Agilent 8753ES or equivalent, typical values at +20 °C

Current derating I_{op}/I_R versus ambient temperature T_A (rated temperature T_R = +60 °C)





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Information about the exterior of VHF chokes

Condition	Criteria			
Winding wire end out of the foil	Max. length until body diameter is allowed			
Winding wire end out under foil	Max. length cannot reach the foil			
Tin accumulation on the lead wire	Max. 1 mm is allowed			
stamping picture, marking readability	The electrical values must be legible			
Insulation foil position (the smallest	Min. 0.8 mm from the edge of the core			
overhang of the insulation foil on the core)	Considering the above dimensions, the insulating foil can also be located asymmetrically on the core			
Position of soldered starting and ending	They can locate outside of the			
turns	insulating foil			
Foil adhesion, upstanding foil	Max. 1 mm upstanding foil is allowed			



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Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.

Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire, wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
 - Many coating materials have a negative effect (chemically and mechanically) on the winding wires, insulation materials and connecting points. Customers are always obligated to determine whether and to what extent their coating materials influence the component. Customers are responsible and bear all risk for the use of the coating material. TDK Electronics does not assume any liability for failures of our components that are caused by the coating material.
- Ceramics / ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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